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	<u> </u>	•	Application Number		00/600 466		
TRANSMITTAL FORM (10 be used for all correspondence after initial filing)					09/699,466		
			Filing Date		October 31, 2000		
			First Named Inventor		Shunpei YAMAZAKI et al.		
			Group Art Unit		2813		
		,7	Examiner Name		Asok SARKAR		
Total Number of Pages in This	Submission		Attorney Docket Numbe	г	740756-2222		
		ENCLOSUI	RES (check all that appl	y)			
Fee Transmittal Form  Fee Attached  Drawing  Amendment / Reply  After Final  Affidavits/declaration(s)  Extension of Time Request  Express Abandonment Request  Information Disclosure Statement  Certified Copy of Priority  Assignm  (for an A  Drawing  Licensin  Petition  Petition  Provision  Change of Address  Terminal  Request		to Convert to a nal Application f Attorney, Revocation of Correspondence		TECHNOLOGY CENTER 2800			
	SIGNATUR	E OF APPLI	CANT, ATTORNEY,	OR AC	GENT		
Firm or Individual name  Luan C. Do Nixon Peabody LLP 8180 Greensboro Drive Suite 800 McLean VA 28012							
Signature							
Date July 2001							
		CERTIFIC	CATE OF MAILING				
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on this date:  7-5-2001							
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Signature	Type or printed name  SKIRILLY B. STRAIN  Signature  Signature  Shirlly B. STRAIN  Date  7-5-01  Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual						
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## THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re P	ATENT applic	ation of:	)	٠. ٨	
	Shunpei YAM	IAZAKI et al.	) ) ) Art Unit:	2813 TO THE CE	
Applic	ation No.:	09/699,466	)	8, 6	
Filed:		October 31, 2000	) Examiner: Asok S	SARKAR CHILE	
For:		R FABRICATING A JCTOR DEVICE	)	72800	

## REQUEST FOR CORRECTION OF PRIOR INFORMATION DISCLOSURE STATEMENT

Commissioner of Patents Washington, D.C. 20231

July 5, 2001

## Dear Sir:

Supplemental to the Information Disclosure Statement filed October 31, 2000, attached hereto is corrected page 6 of Form PTO-1449 to be made of record in the aboveidentified application. Upon further review of the application, the undersigned noticed three typographical errors in the listings of three separate references listed below for which Abstracts had been submitted for each:

> 1. JP 61-63107 published 4/1/86

2. JP 7-16134 published 6/23/95

3. JP 52-99348 published 11/93

Each corrected reference number has been listed in boldtype on the Form PTO-1449 sheet for the Examiner's convenience. Applicants apologize for the inconvenience caused by these errors.

It is requested that this Request For Corrected Information Disclosure Statement be considered and made of record in the above-captioned application. It is respectfully requested that an Examiner-initialed copy of this form be returned to the undersigned. In particular, the

Attorney Docket No.: 740756-2018 Application No.: 09/699,466

Art Unit: 2823

Page 2

Examiner is requested to consider U.S. Patent No. 5,531,182 listed on page 5 of the PTO-1449 form submitted on October 31, 2000.

The Commissioner is hereby authorized to charge any fees connected with this filing which may be required now, or credit any overpayment to Deposit Account No. 19-2380.

Respectfully submitted,

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EJR/LCD:sbs

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